

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>XINYU FU</td> <td>02/19/2008</td> </tr> <tr> <td>KEYVAN KASHEFIZADEH</td> <td>02/20/2008</td> </tr> <tr> <td>ASHISH SUBHASH BODKE</td> <td>02/20/2008</td> </tr> <tr> <td>WINSOR LAM</td> <td>02/19/2008</td> </tr> <tr> <td>YIOCHIRO TANAKA</td> <td>02/25/2008</td> </tr> <tr> <td>WONWOO KIM</td> <td>02/20/2008</td> </tr> </tbody> </table>		Name	Execution Date	XINYU FU	02/19/2008	KEYVAN KASHEFIZADEH	02/20/2008	ASHISH SUBHASH BODKE	02/20/2008	WINSOR LAM	02/19/2008	YIOCHIRO TANAKA	02/25/2008	WONWOO KIM	02/20/2008
Name	Execution Date														
XINYU FU	02/19/2008														
KEYVAN KASHEFIZADEH	02/20/2008														
ASHISH SUBHASH BODKE	02/20/2008														
WINSOR LAM	02/19/2008														
YIOCHIRO TANAKA	02/25/2008														
WONWOO KIM	02/20/2008														
RECEIVING PARTY DATA															
Name:	APPLIED MATERIALS, INC.														
Street Address:	P.O. BOX 450A														
Internal Address:	LEGAL AFFAIRS DEPT.														
City:	SANTA CLARA														
State/Country:	CALIFORNIA														
Postal Code:	95052														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12041804</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12041804										
Property Type	Number														
Application Number:	12041804														
CORRESPONDENCE DATA															
Fax Number:	(408)986-3090														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	408-563-2726														
Email:	robert_mulcahy@contractor.amat.com														
Correspondent Name:	Robert W. Mulcahy														
Address Line 1:	P.O. BOX 450A														
Address Line 2:	LEGAL AFFAIRS DEPT.														
Address Line 4:	SANTA CLARA, CALIFORNIA 95052														
ATTORNEY DOCKET NUMBER:	AM11302/CPI/AG														

CH \$40.00 12041804

PATENT

NAME OF SUBMITTER:

ROBERT W MULCAHY

Total Attachments: 9

source=11302ASG030408#page1.tif

source=11302ASG030408#page2.tif

source=11302ASG030408#page3.tif

source=11302ASG030408#page4.tif

source=11302ASG030408#page5.tif

source=11302ASG030408#page6.tif

source=11302ASG030408#page7.tif

source=11302ASG030408#page8.tif

source=11302ASG030408#page9.tif

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	XINYU FU 48356 Sawleaf Street Fremont, CA 94539	2)	KEYVAN KASHEFIZADEH 4724 Finch Way Dublin, CA 94568
3)	ASHISH SUBHOSH^A BODKE 5068 McCoy Avenue San Jose, CA 95130 <i>ASB</i>	4)	WINSOR LAM 957 Martin Trail Daly City, CA 94014
5)	YIOCHIRO TANAKA 56 Cabot Avenue Santa Clara, CA 95054	6)	WONWOO KIM 7036 Anjou Creek Circle San Jose, CA 95120

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHODS OF FORMING A LAYER FOR BARRIER APPLICATIONS
IN AN INTERCONNECT STRUCTURE**

enclosed herewith or for which application for Letters Patent in the United States was filed on _____, under Serial No. _____, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said

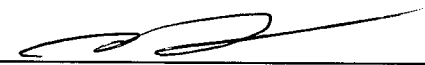

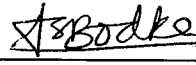

Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting conventional, substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

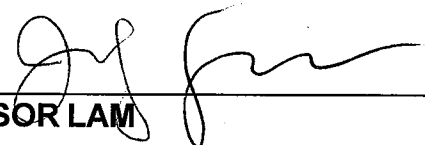
3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>2/19/08</u> (DATE)	 _____ XINYU FU
2)	<u>2/20/08</u> (DATE)	 _____ KEYVAN KASHEFIZADEH
3)	<u>2/20/08</u> (DATE)	 _____ ASHISH SUBHOSH BODKE A 

4) 2/19/08 (DATE)



WINSOR LAM

5) _____ (DATE)

YIOCHIRO TANAKA

6) _____ (DATE)

WONWOO KIM

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	XINYU FU 48356 Sawleaf Street Fremont, CA 94539	2)	KEYVAN KASHEFIZADEH 4724 Finch Way Dublin, CA 94568
3)	ASHISH SUBHOSH BODKE 5068 McCoy Avenue San Jose, CA 95130	4)	WINSOR LAM 957 Martin Trail Daly City, CA 94014
5)	YIOCHIRO TANAKA 56 Cabot Avenue Santa Clara, CA 95054	6)	WONWOO KIM 7036 Anjou Creek Circle San Jose, CA 95120

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHODS OF FORMING A LAYER FOR BARRIER APPLICATIONS
IN AN INTERCONNECT STRUCTURE**

enclosed herewith or for which application for Letters Patent in the United States was filed on _____, under Serial No. _____, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said

Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents; giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting conventional, substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____ (DATE) _____
XINYU FU

2) _____ (DATE) _____
KEYVAN KASHEFIZADEH

3) _____ (DATE) _____
ASHISH SUBHOSH BODKE

4) _____ (DATE)

WINSOR LAM

5) 2/25/08 (DATE)

Yi-Chiro Tanaka
YI-CHIRO TANAKA

6) _____ (DATE)

WONWOO KIM

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	XINYU FU 48356 Sawleaf Street Fremont, CA 94539	2)	KEYVAN KASHEFIZADEH 4724 Finch Way Dublin, CA 94568
3)	ASHISH SUBHOSH BODKE 5068 McCoy Avenue San Jose, CA 95130	4)	WINSOR LAM 957 Martin Trail Daly City, CA 94014
5)	YIOCHIRO TANAKA 56 Cabot Avenue Santa Clara, CA 95054	6)	WONWOO KIM 7036 Anjou Creek Circle San Jose, CA 95120

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHODS OF FORMING A LAYER FOR BARRIER APPLICATIONS
IN AN INTERCONNECT STRUCTURE**

enclosed herewith or for which application for Letters Patent in the United States was filed on _____, under Serial No. _____, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said

Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting conventional, substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____ (DATE) _____
XINYU FU

2) _____ (DATE) _____
KEYVAN KASHEFIZADEH

3) _____ (DATE) _____
ASHISH SUBHOSH BODKE

4) _____ (DATE)

WINSOR LAM

5) _____ (DATE)

YIOCHIRO TANAKA

6) 02/20/08 (DATE)



WONWOO KIM